

2142 1024 X 4 BIT STATIC RAM

	2142-2	2142-3	2142	2142L3	2142L
Max. Access Time (ns)	200	300	450	300	450
Max. Power Dissipation (mw)	525	525	525	370	370

- High Density 20 Pin Package
- Access Time Selections From 200-450ns
- Identical Cycle and Access Times
- Low Operating Power Dissipation .1mW/Bit Typical
- Single +5V Supply

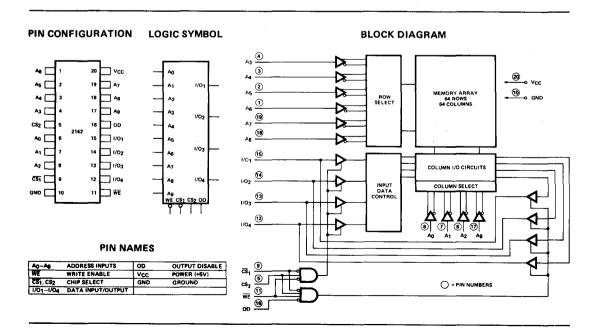
- No Clock or Timing Strobe Required
- Completely Static Memory
- Directly TTL Compatible: All Inputs and Outputs
- Common Data Input and Output Using Three-State Outputs

The Intel® 2142 is a 4096-bit static Random Access Memory organized as 1024 words by 4-bits using N-channel Silicon-Gate MOS technology. It uses fully DC stable (static) circuitry throughout — in both the array and the decoding — and therefore requires no clocks or refreshing to operate. Data access is particularly simple since address setup times are not required. The data is read out nondestructively and has the same polarity as the input data. Common input/output pins are provided.

The 2142 is designed for memory applications where high performance, low cost, large bit storage, and simple interfacing are important design objectives. It is directly TTL compatible in all respects: inputs, outputs, and a single +5V supply.

The 2142 is placed in a 20-pin package. Two Chip Selects ($\overline{\text{CS}}_1$ and CS_2) are provided for easy and flexible selection of individual packages when outputs are OR-tied. An Output Disable is included for direct control of the output buffers.

The 2142 is fabricated with Intel's N-channel Silicon-Gate technology — a technology providing excellent protection against contamination permitting the use of low cost plastic packaging.



ABSOLUTE MAXIMUM RATINGS*

Temperature Under Bias10°C to 80°C
Storage Temperature65°C to +150°C
Voltage on Any Pin
With Respect to Ground0.5V to +7V
Power Dissipation 1.0W
D.C. Output Current

*COMMENT: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

D.C. AND OPERATING CHARACTERISTICS

 $T_A = 0^{\circ}C$ to $70^{\circ}C$, $V_{CC} = 5V \pm 5\%$, unless otherwise noted.

SYMBOL	PARAMETER		, 2142-3, Typ.[1]		2142L3 Min.	, 2142L Typ.[1]	Max.	UNIT	CONDITIONS
(Iu)	input Load Current (All Input Pins)			10			10	μА	V _{IN} = 0 to 5.25V
ILOI	I/O Leakage Current			10			10	μΑ	$\overline{CS} = 2.4V,$ $V_{1/O} = 0.4V \text{ to } V_{CC}$
l _{CC1}	Power Supply Current		80	95			65	mA	$V_{IN} = 5.25V$, $I_{I/O} = 0$ mA, $T_A = 25^{\circ}C$
I _{CC2}	Power Supply Current			100			70	mA	$V_{IN} = 5.25V$, $I_{I/O} = 0$ mA, $T_A = 0^{\circ}C$
VIL	Input Low Voltage	-0.5		8.0	-0.5	· · · · · · · · ·	0.8	٧	
V _{IH}	Input High Voltage	2.0		6.0	2.0		6.0	V	
loL	Output Low Current	2.1	6.0		2.1	6.0		mA	V _{OL} = 0.4V
ЮН	Output High Current	-1.0	-1.4		-1.0	-1.4		mA	V _{OH} = 2.4V
los ^[2]	Output Short Circuit Current			60			60	mA	V _{OUT} = V _{CC} to GND

NOTE: 1. Typical values are for $T_A = 25^{\circ} C$ and $V_{CC} = 5.0 V$.

2. Duration not to exceed 30 seconds.

CAPACITANCE

TA = 25°C, f = 1.0 MHz

SYMBOL	TEST	MAX	UNIT	CONDITIONS
CI/O	Input/Output Capacitance	5	pF	V _{I/O} = OV
C _{IN}	Input Capacitance	5	pF	V _{IN} ≈ OV

NOTE: This parameter is periodically sampled and not 100% tested.

A.C. CONDITIONS OF TEST

Input Pulse Levels
Input Rise and Fall Times
Input and Output Timing Levels
Output Load 1 TTL Gate and C _L = 100 pF

A.C. CHARACTERISTICS $T_A = 0^{\circ}C$ to $70^{\circ}C$, $V_{CC} = 5V \pm 5\%$, unless otherwise noted.

READ CYCLE [1]

SYMBOL	PARAMETER	2142-2 Min. Max	2142-3, 2142L3 Min. Max.	2142, 2142L Min. Max.	UNIT
tRC	Read Cycle Time	200	300	450	ns
t _A	Access Time	200	300	450	ns
top	Output Enable to Output Valid	70	100	120	ns
topx	Output Enable to Output Active	20	20	20	ns
tco	Chip Selection to Output Valid	70	100	120	ns
tcx	Chip Selection to Output Active	20	20	20	ns
^t OTD	Output 3-state from Disable	60	80	100	ns
toha	Output Hold from Address Change	50	50	50	ns

WRITE CYCLE [2]

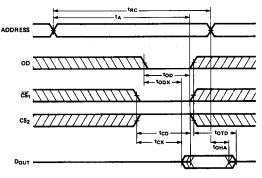
		2142-2		2142-3,	2142L3	2142, 2142L		
SYMBOL	PARAMETER	Min.	Max.	Min.	Max.	Min.	Max.	UNIT
twc	Write Cycle Time	200		300		450		ns
tw	Write Time	120		150		200		ns
twn	Write Release Time	0		0		0		ns
^t OTD	Output 3-state from Disable		60		80		100	ns
t _{DW}	Data to Write Time Overlap	120		150		200	-	ns
t _{DH}	Data Hold From Write Time	0		0		0		ns

NOTES:

- 1. A Read occurs during the overlap of a low $\overline{\text{CS}}$ and a high $\overline{\text{WE}}$.
- 2. A Write occurs during the overlap of a low CS and a low WE.

WAVEFORMS

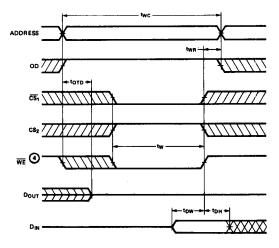
READ CYCLE®



NOTES:

- 3. WE is high for a Read Cycle.
- 4. WE must be high during all address transitions.

WRITE CYCLE



TYPICAL D.C. AND A.C. CHARACTERISTICS

